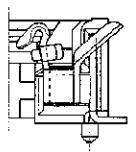
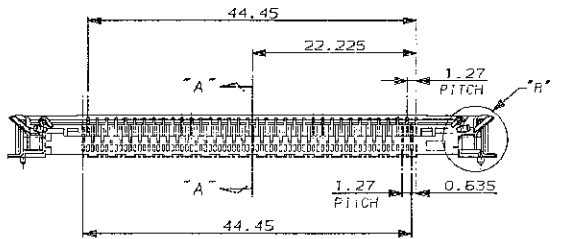
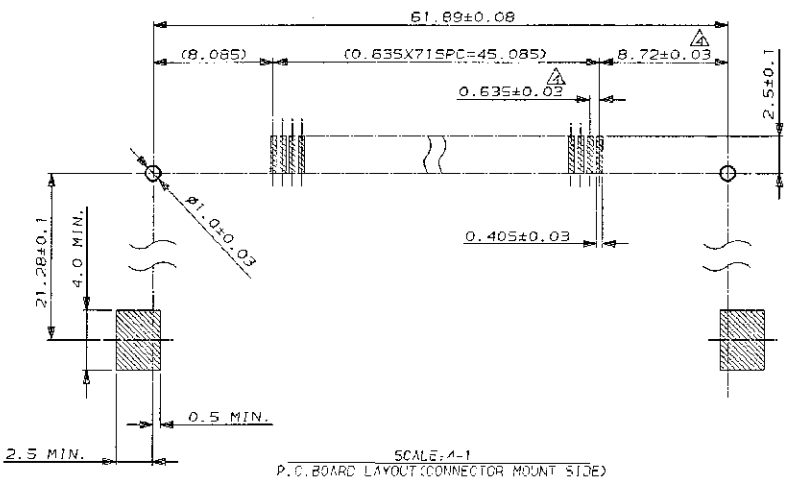


- NOTES**
- MATERIAL & FINISH  
 HOUSING : GLASS FILLED LCP  
 CONTACT : COPPER ALLOY  
 FINISH--SEE NOTES  
 LATCH : COPPER ALLOY, TIN PL.  
 CONTACT PLATING (AU PL. TYPE)  
 Au(0.3µm)PL. AT CONTACT, TIN PL. AT  
 TINE OVER NI PL.  
 CONTACT PLATING (TIN PL. TYPE)  
 TIN PL. (2µm) OVER NI PL.  
 TOLERANCE : NON CUMULATIVE.  
 CONTACT PLATING (AU PL. TYPE)  
 Au(1.27µm)PL. AT CONTACT, TIN PL. AT  
 TINE OVER NI PL.
- 6** OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER  
 D.RENAUD/D.SINISI



DETAIL "B"  
 (SCALE: 5-1)



SCALE: 1-1  
 P.C. BOARD LAYOUT (CONNECTOR MOUNT SIDE)

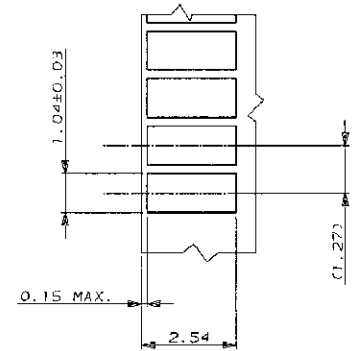
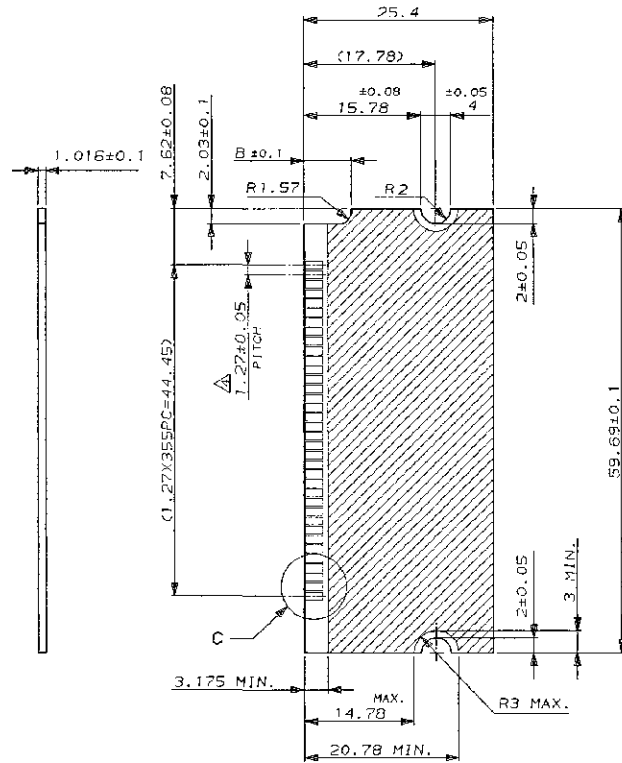
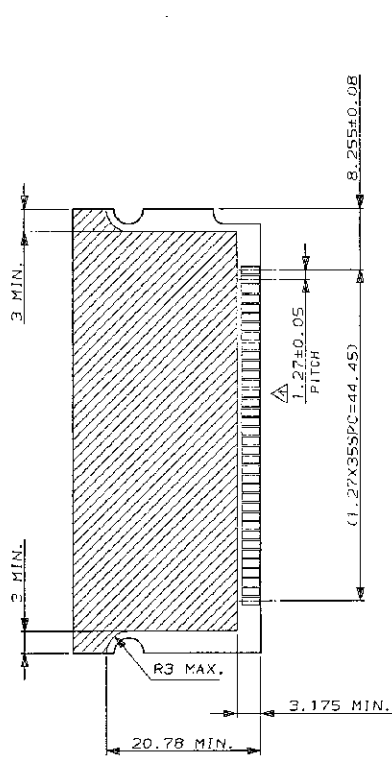
6	OBSOLETE	NATURAL	2.95	1.27µm Au	5177827-4
		BLACK	6.15	0.3µm Au	5177827-3
6	OBSOLETE	NATURAL	1.0	0.3µm Au	5177827-2
		HOUSING COLOR	C	A	PLATING (CONTACT POINT) PART No.

**TE** TE Connectivity

M III SOCKET

WIRE GAUGE	INSULATION THICKNESS	NAME
MATERIAL	FINISH	ASSEMBLY
SEE NOTES	SEE NOTES	GENERAL TOLERANCES
		LOC
		REV. 2
		REV. 1
		REV. 3

P	ECO-11-005033	RK	HMR	APR	DR. LEO ZHOU	15SEP05	DE.	SCALE 2-1	REV. 2	C	J	C-5177827
LIK	(REVISION REQUIRED)	DR	CHK	DATE	CHK. T. KAWAMAE	15SEP05	APP. STEVEN YACOBSON					1 OF 2



DETAIL C (SCALE: 10-1)

 COMPONENT AREA

(SMALL OUTLINE SIMM)  
RECOMMENDED DIMENSIONS OF "SMALL OUTLINE SIMM" P.C. BOARD

6.35	5.0V
3.175	3.3V
B	CIRCUIT VOLTAGE

<p>SEE SHEET D</p>		<p>WIRE GAUGE (MATERIAL)</p>		<p>(INSULATION DIA.)</p>		<p>(NAME)</p>	
		<p>SEE NOTES</p>		<p>SEE NOTES</p>		<p>M III SOCKET</p>	
LTR	(REVISION RECORD)	DR	CHK	DATE	CHK	APP.	<p>REV. P</p> <p>SHEET 2 OF 2</p>